PDR | REWORK

IR-E2 BGA REWORK STATION

Focused Infrared Precision, Zero Compromise.

OVERVIEW

The IR-E2 builds on the IR-E1 platform, offering increased flexibility and process capability for a wider range of PCB sizes and rework applications. Combining Focused Infrared heating with controlled preheating, accurate sensing, and intuitive software, it delivers stable, repeatable results across varied rework processes.

KEY ADVANTAGES

FOCUSED INFRARED HEATING

- Visible, targeted focused IR heating directly to the component
- No damage to surrounding components
- Precise and adjustable energy for safe rework

PCB PREHEATER

- Protects components and PCBs from thermal shock
- Fast, even zonal PCB heating
- Reduces thermal gradients, warping, and board stress

THERMOACTIVE SOFTWARE

- Simple, intuitive interface for process control
- Automated temperature profiling and monitoring
- Ensures consistent, repeatable rework performance

SENSORS

- Non-contact infrared sensor for component temperature measurement
- Contact probe for accurate PCB temperature monitoring
- Enables independent control of component and PCB temperatures

ALIGNMENT SYSTEM

- Manual optical alignment system
- Accurate component positioning
- Designed for reliable, repeatable placement

TECHNICAL SPECIFICATIONS

Max PCB Size: 12 x 18"/300 x 450mm

Max Component Size: 2.1 x 2.1"/55 x 55mm

Min Component Size: 01005

Component Removal: Manual Pick-Up System

Component Placement: Split Beam Prism Alignment/x50 Magnification

Placement Accuracy: Up to 10um

Top Heater Power: 150W Focused Infrared up to Ø70mm Spot

PCB Preheater Power: 2800W Medium-Wave IR (3 Zones)

PCB Preheater Heating Area Size: 14.1 x 9.4"/360 x 240mm

Component Temperature Sensing: Non-Contact IR Sensor

PCB Temperature Sensing: Contact Probe

Number of TC Channels: 4